



Materials Declaration

Package	LFCSP
Body Size	9 X 9 X 0.85 (6.2 mm EP)
LeadCount	64
Option	Pb-free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SIO2 Filler	86.9	9.32 E-02	476496
Epoxy & Phenol Resin	12.8	1.37 E-02	70066
Carbon black	0.3	3.32 E-04	1698
Subtotal		1.07 E-01	548260

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	97.62	7.08 E-02	361985
Fe	2.19	1.59 E-03	8126
Zn	0.11	8.20 E-05	419
P	0.07	5.30 E-05	271
Subtotal		7.25 E-02	370801

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	7.13 E-04	3646

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	3.00 E-04	1534

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	1.58 E-03	8060

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	1.14 E-02	58340

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	73	1.34 E-03	6873
Epoxy Resin	18	3.36 E-04	1718
Metal oxide	3	5.00 E-05	256
Curing and hardening agent	3	5.00 E-05	256
Gamma Butyrolactone	3	5.00 E-05	256
Subtotal		1.83 E-03	9359

Package Totals	
Weight (g)	PPM
1.96 E-01	1000000

Item	PPM	Method
Pb	Not Detected	US EPA 3052, ICP-OES
Cd	Not Detected	US EPA 3052, ICP-OES
Hg	Not Detected	US EPA 3052, ICP-OES
Cr+6	Not Detected	EPA 3060A & 7196A, UV-VIS
PBB	Not Detected	USEPA 3540C/3550C. Analysis performed by GC/MS
PBDE	Not Detected	USEPA 3540C/3550C. Analysis performed by GC/MS

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Note: The information provided in this declaration are true to the best of ADI's knowledge
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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